

July 31, 2025

Mr. Duane E. White  
Chief  
Low-Level Waste and Projects Branch  
U.S. Nuclear Regulatory Commission  
11555 Rockville Pike  
Rockville, MD 20852-2738

**Re: Application Supplement to the License Application for a Performance-Based, Multi-Site Radioactive Materials License to Operate a High-Pressure Slurry Ablation Remediation System, Revision 3, DISA Technologies, Inc.  
Docket No. 40-38417**

Dear Mr. White:

By letter dated June 2, 2025, the U.S. Nuclear Regulatory Commission (NRC) staff issued several requests for additional information (RAIs) (Agencywide Documents Management and Access System [ADAMS] Accession No. ML25141A028) to support its review of DISA Technologies, Inc.'s (DISA's) license application dated March 21, 2025 (ML25087A094) for a multi-site, radioactive materials license for our High-Pressure Slurry Ablation technology to remediate uranium mine waste. Disa responded to these RAIs in letter dated June 16, 2025 (ML25167A328). By letter dated July 8, 2025, the NRC staff issued an audit plan to resolve outstanding issues related to DISA's June 16, 2025, RAI response letter. This audit occurred from July 11 through July 29, 2025.

During the audit, DISA prepared an application supplement that addressed the issues discussed during the audit. Attached to this letter is the finalized application supplement along with attachments containing additional information. DISA is also completing revisions to its standard operating procedures and a quality assurance project plan. These documents will be submitted by August 4, 2025.

DISA appreciates the staff's efforts in completing this review and this opportunity to resolve the NRC staff's issues. If you have any questions, please contact me.

Sincerely,

A handwritten signature in black ink, which appears to read "Stephen J. Cohen". The signature is fluid and cursive.

Stephen J. Cohen, CRAO  
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cc: P. Yadav  
I. Johnston  
K. Pinkston  
C. Pineda  
D. Mandeville  
A. Kock

Attachments: 1. Application Supplement